



- 1 RIE processed lens array in glass.
- 2 Cross section of etched cylindrical lenses.
- 3 Conical lens profile ($NA=0.25$, $k=-2$) dry etched in fused silica.
- 4 Chip diced optical element with double-sided aligned and focus matched cylinder lens arrays in borosilicate glass.

MICRO OPTICS IN FUSED SILICA, BOROSILICATE GLASS AND SILICON

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Objective

Fabrication of micro-optical elements with high durability, high laser damage threshold and transparency ranging from UV to IR in fused silica, borosilicate glass and silicon

Characteristics

- Spherical and cylindrical lenses
- Diffractive elements
- Arrays with sub- μm position accuracy
- Aspherical lens profiles
- Lens sag up to approx. 50 μm
- Uniformity $\pm 2\%$ on 100 mm Wafer
- Reproducibility $\pm 2\%$
- rms profile accuracy $\pm 0.3\%$ of lens height within 95% of lens diameter
- Base material: Wafer \varnothing 100/150 mm, up to ca. 6 mm thickness

Application

- UV, VIS and IR-optics
- Laser / Fiber-collimation
- Beam forming elements
- Homogenisation
- Fill factor enhancement of detector arrays

Technology

- Wafer-scale process technology on silicon, fused silica or borosilicate glass
- Primary pattern generation by lithography and polymer reflow or variable dose laser lithography
- Proportional transfer by plasma dry etching (RIE, ICP)
- Double-sided aligned processing
- Surface AR-Coatings
- Separation by chip dicing